

1. Canceled.
2. Canceled.
3. Canceled.
4. Canceled.
5. Canceled.
6. Canceled.
7. Canceled.
8. Canceled.
9. Canceled.
10. Canceled.
11. Canceled.
12. Canceled.
13. Canceled.
14. Canceled.
15. Canceled.
16. Canceled.
17. Canceled.
18. Canceled.
19. Cancel.
20. Cancel.
21. Cancel.
22. Cancel.
23. Cancel.
24. Cancel.
25. Cancel.
26. Canceled.
27. Canceled.
28. Canceled.
29. Canceled.

- 30. Canceled.
- 31. Canceled.
- 32. Canceled.
- 33. Canceled.
- 34. Canceled.
- 35. Canceled.
- 36. Canceled.
- 37. Canceled.
- 38. Canceled.
- 39. Canceled.
- 40. Canceled.
- 41. Canceled.
- 42. Canceled.
- 43. Canceled.
- 44. Canceled.
- 45. Canceled.
- 46. Canceled.
- 47. Canceled.
- 48. Canceled.
- 49. Canceled.
- 50. Canceled.
- 51. Canceled.
- 52. Canceled.
- 53. Canceled.
- 54. Canceled.
- 55. Canceled.
- 56. Canceled.
- 57. Canceled.
- 58. Canceled.

- 59. Cancel.
- 60. Canceled.
- 61. Canceled.
- 62. Cancel.
- 63. Cancel.

Chi 1
F1
Sub
GI
Chi 2

64. (New) A wafer processing apparatus comprising:
a wafer holder adapted to receive a wafer having an electrical coupling, the wafer holder including an electrical coupling configured to electrically couple with the electrical coupling of the wafer and communicate signals between the wafer and the wafer holder.

65. (New) The wafer processing apparatus according to claim 64 further comprising a data gathering device coupled with the electrical coupling of the wafer holder and configured to receive the signals.

Chi 3

66. (New) The wafer processing apparatus according to claim 65 further comprising a contact plate configured to communicate the signal intermediate the wafer holder and the data gathering device.

Chi 4

67. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder includes a first surface, a second surface, and an electrical interconnect configured to electrically couple the first surface and the second surface.

Claim 5
68. (New) The wafer processing apparatus according to claim 67 wherein the first surface of the wafer holder is configured to face a received wafer and the second surface is configured to face a chuck.

Claim 6
69. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder includes a plurality of electrical couplings adapted to couple with a plurality of electrical couplings of the wafer.

FI Cont
Field
Ch 1
70. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder comprises a chuck.

Ch 8
71. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder comprises a chuck configured to receive one of a calibration wafer and a production wafer.

Ch 9
72. (New) The wafer processing apparatus according to claim 71 wherein the wafer holder includes vacuum chambers adapted to receive a vacuum to couple one of the calibration wafer and the production wafer with the chuck.

Ch 10
73. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder comprises an intermediate member adapted to couple with a chuck.

74. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder includes a vacuum chamber adapted to receive a vacuum to couple a received wafer with the wafer holder.

75. (New) The wafer processing apparatus according to claim 64 wherein the ^{NAB} electrical interconnect comprises a conductive column configured to extend outward from plural surfaces of the wafer holder.

76. (New) The wafer processing apparatus according to claim 75 further comprising a contact plate including circuitry configured to provide electrical connection with the conductive column.

77. (New) The wafer processing apparatus according to claim 64 wherein the ^{NAB} electrical coupling of the workpiece holder is adapted to contact the electrical coupling of the wafer.

78. (New) The wafer processing apparatus according to claim 64 wherein the wafer holder is adapted to expose the wafer to a processing environment to process the wafer.

79. (New) A wafer processing apparatus comprising:

chills
a wafer holder having circuitry configured to communicate a process signal from a received wafer and the process signal containing information regarding processing of the wafer.

grip
80. (New) The wafer processing apparatus according to claim 79 wherein the wafer holder is adapted to expose the wafer to a processing environment to process the wafer.

Fl Cont
(19)
81. (New) A wafer processing apparatus comprising:

a chuck including a surface, an electrical coupling adjacent the surface, and electrical interconnect configured to connect with the electrical coupling of the chuck and conduct a signal within the chuck;

an intermediate member adapted to receive a wafer and the intermediate member having a first surface and a second surface and the intermediate member including:

an electrical coupling adjacent the first surface and configured to couple with the electrical coupling of the chuck;

an electrical coupling adjacent the second surface; and

an electrical interconnect configured to connect the electrical coupling adjacent the first surface and the electrical coupling adjacent the second surface; and

a wafer configured to couple with the second surface of the intermediate member, the wafer including a sensor and an electrical coupling configured to provide electrical

connection of the sensor with the electrical coupling of the second surface of the intermediate member.

Sub
81
82. (New) The wafer processing apparatus according to claim 81 further comprising a data gathering device coupled with the electrical coupling of the chuck and configured to receive the signal.

FI
cont
ch 21
83. (New) The wafer processing apparatus according to claim 82 further comprising a contact plate configured to communicate the signal intermediate the chuck and the data gathering device.

ch 22
84. (New) The wafer processing apparatus according to claim 81 wherein the sensor comprises a resistance temperature device.

ch 23
85. (New) The wafer processing apparatus according to claim 81 wherein the wafer comprises a calibration wafer.

ch 24
86. (New) The wafer processing apparatus according to claim 81 wherein the electrical interconnect comprises a conductive column configured to extend outward from plural surfaces of the chuck.

claim 25
N
87. (New) The wafer processing apparatus according to claim 86 further comprising a contact plate including circuitry configured to provide electrical connection with electrical couplings of the chuck.

sub
81
88. (New) The wafer processing apparatus according to claim 81 wherein the intermediate member is configured to expose the wafer to a processing environment to process the wafer.

F1
cont
claim 26
89. (New) A wafer processing apparatus comprising:
a chuck including a surface, a plurality of electrical couplings adjacent the surface,
and a plurality of electrical interconnects configured to connect with respective electrical couplings of the chuck and conduct signals within the chuck;

an intermediate member adapted to receive a wafer and the intermediate member having a first surface and a second surface and the intermediate member including:

a plurality of electrical couplings adjacent the first surface and configured to couple with respective electrical couplings of the chuck;

a plurality of electrical couplings adjacent the second surface; and

a plurality of electrical interconnects configured to electrically connect the electrical couplings of the first surface with respective electrical couplings of the second surface;

a calibration wafer configured to couple with the second surface of the intermediate member, the calibration wafer including a plurality of resistance temperature devices

claim 46
Sub
GA
configured to generate process signals, and a plurality of electrical connections configured to electrically connect the resistance temperature devices with respective electrical couplings of the second surface of the intermediate member; and

a data gathering device coupled with the electrical interconnects of the chuck and configured to receive the process signals from the resistance temperature devices through the intermediate member and the chuck.

FI
Cont
90. (New) The wafer processing apparatus according to claim 89 wherein the intermediate member is configured to expose the wafer to a processing environment to process the wafer.

claim 57
O.K.
91. (New) An electronic device workpiece processing apparatus comprising:
a workpiece holder adapted to receive an electronic device workpiece having an electrical coupling, the workpiece holder including an electrical coupling configured to electrically couple with the electrical coupling of the electronic device workpiece and communicate signals between the electronic device workpiece and the workpiece holder, wherein the workpiece holder includes a vacuum chamber adapted to receive a vacuum to couple a received electronic device workpiece with the workpiece holder.

92. (New) The apparatus of claim 91 wherein the workpiece holder is configured to expose the electronic device workpiece to a processing environment to process the electronic device workpiece.

Ch 58
Sub G
Fl Cont

93. (New) An electronic device workpiece processing apparatus comprising:
a workpiece holder adapted to receive an electronic device workpiece having an electrical coupling, the workpiece holder including an electrical coupling configured to electrically couple with the electrical coupling of the electronic device workpiece and communicate signals between the electronic device workpiece and the workpiece holder, wherein the electrical coupling of the workpiece holder is configured to extend outward from plural surfaces of the workpiece holder; and
a contact plate including circuitry configured to provide electrical connection with the conductive column.

94. (New) The apparatus of claim 93 wherein the workpiece holder is configured to expose the electronic device workpiece to a processing environment to process the electronic device workpiece.

Ch 59
N

95. (New) An electronic device workpiece processing apparatus comprising:
a chuck including a surface, an electrical coupling adjacent the surface, and electrical interconnect configured to connect with the electrical coupling of the chuck and conduct a signal within the chuck;
an intermediate member having a first surface and a second surface and the intermediate member including:
an electrical coupling adjacent the first surface and configured to couple with the electrical coupling of the chuck;

an electrical coupling adjacent the second surface; and

an electrical interconnect configured to connect the electrical coupling adjacent the first surface and the electrical coupling adjacent the second surface;

an electronic device workpiece configured to couple with the second surface of the intermediate member, the electronic device workpiece including a sensor and an electrical coupling configured to provide electrical connection of the sensor with the electrical coupling of the second surface of the intermediate member;

a data gathering device coupled with the electrical coupling of the chuck and configured to receive the signal; and

a contact plate configured to communicate the signal intermediate the chuck and the data gathering device.

96. (New) The apparatus of claim 95 wherein the intermediate member is configured to expose the electronic device workpiece to a processing environment to process the electronic device workpiece.

97. (New) An electronic device workpiece processing apparatus comprising:
a chuck including a surface, an electrical coupling adjacent the surface, and electrical interconnect configured to connect with the electrical coupling of the chuck and conduct a signal within the chuck;

an intermediate member having a first surface and a second surface and the intermediate member including:

an electrical coupling adjacent the first surface and configured to couple with the electrical coupling of the chuck;

an electrical coupling adjacent the second surface; and

an electrical interconnect configured to connect the electrical coupling adjacent the first surface and the electrical coupling adjacent the second surface; and

an electronic device workpiece configured to couple with the second surface of the intermediate member, the electronic device workpiece including a sensor comprising a resistance temperature device, and an electrical coupling configured to provide electrical connection of the sensor with the electrical coupling of the second surface of the intermediate member.

98. (New) The apparatus of claim 97 wherein the intermediate member is configured to expose the electronic device workpiece to a processing environment to process the electronic device workpiece.

99. (New) An electronic device workpiece processing apparatus comprising:
a chuck including a surface, an electrical coupling adjacent the surface, and electrical interconnect configured to connect with the electrical coupling of the chuck and conduct a signal within the chuck;

a contact plate including circuitry configured to provide electrical connection with the electrical coupling of the chuck;

an intermediate member having a first surface and a second surface and the

intermediate member including:

an electrical coupling adjacent the first surface and configured to couple with the electrical coupling of the chuck;

an electrical coupling adjacent the second surface; and

an electrical interconnect configured to connect the electrical coupling adjacent the first surface and the electrical coupling adjacent the second surface, wherein the electrical interconnect comprises a conductive column configured to extend outward from plural surfaces of the chuck; and

an electronic device workpiece configured to couple with the second surface of the intermediate member, the electronic device workpiece including a sensor and an electrical coupling configured to provide electrical connection of the sensor with the electrical coupling of the second surface of the intermediate member.

100. (New) The apparatus of claim 99 wherein the intermediate member is adapted to expose the electronic device workpiece to a processing environment to process the electronic device workpiece.

101. (New) An electronic device workpiece processing apparatus comprising:
an electronic device workpiece including a sensor and an electrical coupling; and
an intermediate member including a surface having an electrical coupling and adapted to expose the electronic workpiece to a processing environment to process the wafer;

wherein the electrical coupling of the electronic device workpiece is configured to provide electrical connection of the sensor with the electrical coupling of the surface of the intermediate member.

102. (New) The apparatus according to claim 101 wherein the electronic device workpiece comprises a wafer.